

1-1932000-1 ✓ ACTIVE

DDR3 DIMM, DDR3 SO DIMM

TE Internal #: 1-1932000-1

DDR3 DIMM, DIMM Sockets, Double Data Rate (DDR) 3, Board-to-Board, 240 Position, Through Hole - Solder, Vertical Module

Orientation

[View on TE.com >](#)



Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR3 DIMM SOCKETS



DRAM Type: **Double Data Rate (DDR) 3**

Connector System: **Board-to-Board**

Number of Positions: **240**

PCB Mounting Style: **Through Hole - Solder**

Module Orientation: **Vertical**

[All DDR3 DIMM SOCKETS \(13\)](#)

Features

Product Type Features

Center Post	With
DRAM Type	Double Data Rate (DDR) 3
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Center Key	Center
Number of Keys	1
Number of Bays	2
Number of Positions	240
Module Orientation	Vertical
Keying	Standard



Number of Rows	2
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Electrical Characteristics

DRAM Voltage	1.5 V
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Body Features

Ejector Material Color	Natural
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Retention Post Material	Brass
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Ejector Material	High Temperature Nylon
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Ejector Location	Both Ends
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Latch Material	Thermoplastic
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Module Key Type	Offset Left
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Latch Color	Natural
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Retention Post Location	Center
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Ejector Type	Standard
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Contact Features

Socket Style	DIMM
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Contact Underplating Material	Nickel
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PCB Contact Termination Area Plating Material	Tin
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Contact Base Material	Copper Alloy
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Contact Current Rating (Max)	.75 A
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Contact Mating Area Plating Material	Gold
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Contact Mating Area Plating Thickness	.38 μm [15 μin]
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Solder Tail Contact Plating Thickness	3 μm [118.1 μin]
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Socket Type	Memory Card
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Termination Features

Insertion Style	Direct Insert
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Termination Post Length	3.18 mm[.125 in]
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Mechanical Attachment

PCB Mount Retention	With
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PCB Mount Retention Type	Retention Clip/Post
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PCB Mounting Style	Through Hole - Solder
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Connector Mounting Type	Board Mount
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Boardlock Material	Brass
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Mounting Angle	Vertical
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Housing Features

Centerline (Pitch)	1 mm[.039 in]
Housing Material	High Temperature Nylon
Housing Color	Black

Dimensions

Center Retention Hole Diameter	1.8 mm[.07 in]
Height Above PC Board	23.1 mm[.9 in]
Row-to-Row Spacing	1.9 mm[.075 in]

Usage Conditions

Operating Temperature Range	-55 – 155 °C[-67 – 311 °F]
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Operation/Application

Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Tray
Packaging Quantity	50

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 260°C

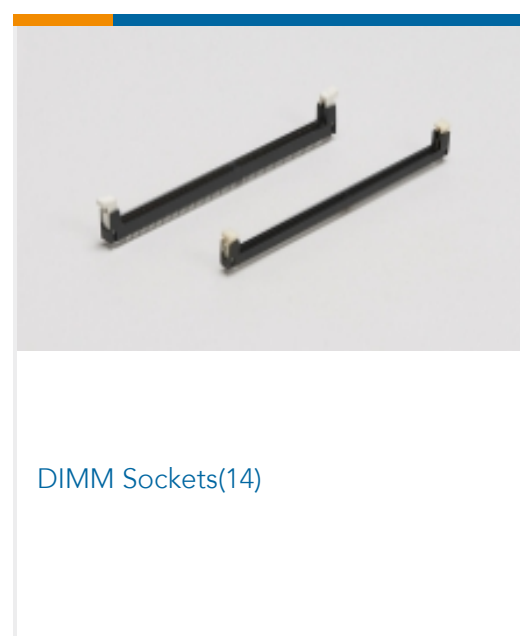
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

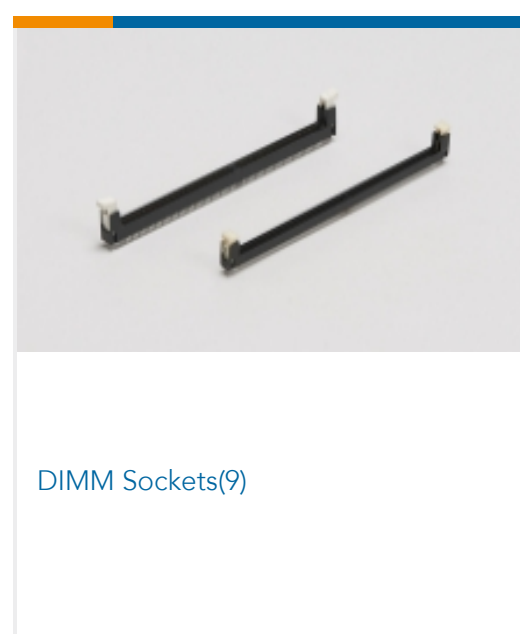
Compatible Parts



Also in the Series | DDR3 DIMM



Also in the Series | DDR3 SO DIMM



Customers Also Bought



Documents

Product Drawings

[VERTICAL DDR3 DIMM, 240 POSITION](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_1-1932000-1_F.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-1932000-1_F.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-1932000-1_F.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages



6-1773457-3_DDR3_DIMM_SOCKETS

Product Specifications

Product Specification

English

Product Environmental Compliance

MD_1-1932000-1_01302018150_dmtec

English

MD_1-1932000-1_01302018150_dmtec

English